



Smart-Pixel TPC

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Motivation (I)

❑ Some **current/future HEP exp.** target for discovery & precision.

→ bigger detector

(HL-)LHC, DUNE

→ high-intensity beam

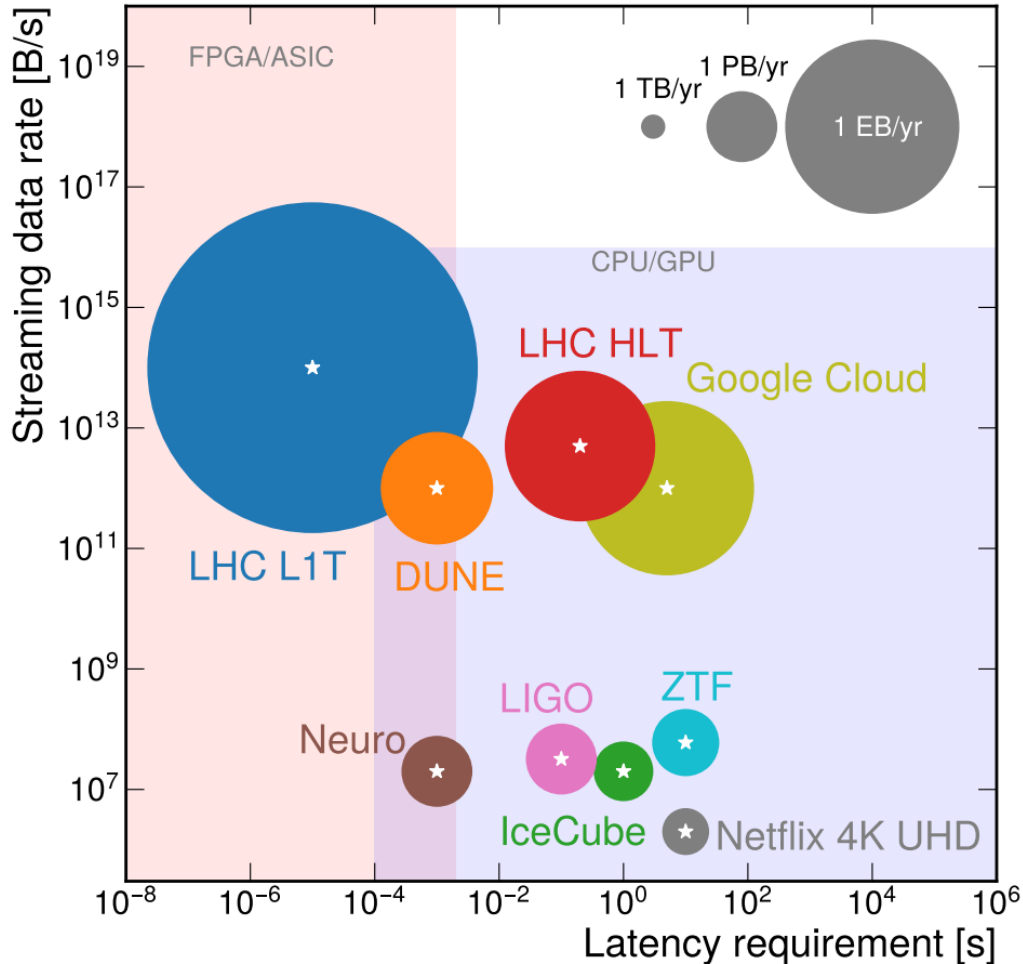
➔ Demand more **“resources”**

- Computing (storage, processors)
- Materials (channels, cables, etc)
- Energy (electricity)

➔ Will increase project/research **“budget”**

Motivation (II)

A3D3 Institute



→ We expect high raw data volumes for (HL-)LHC and DUNE.

□ DUNE: [arXiv:2203.16255](https://arxiv.org/abs/2203.16255)

- \sim TB/sec → **~ 32 EB/year**
- 100 % livetime (for Supernova)
- $>$ ~ 20 years of operation

□ DUNE's cap for computing:
 ~ 30 PB/year

→ **3 orders of magnitude reduction is needed.**

Proposed Solution

❑ AI/ML “*in-situ*” → Reducing computing resources

- Reducing raw data volume by applying AI/ML “*in-situ*”
- Use **all subdetector info “*in-situ*”** to increase S/B

→ **Unique & Challenging**

❑ RF network → Reducing use of materials

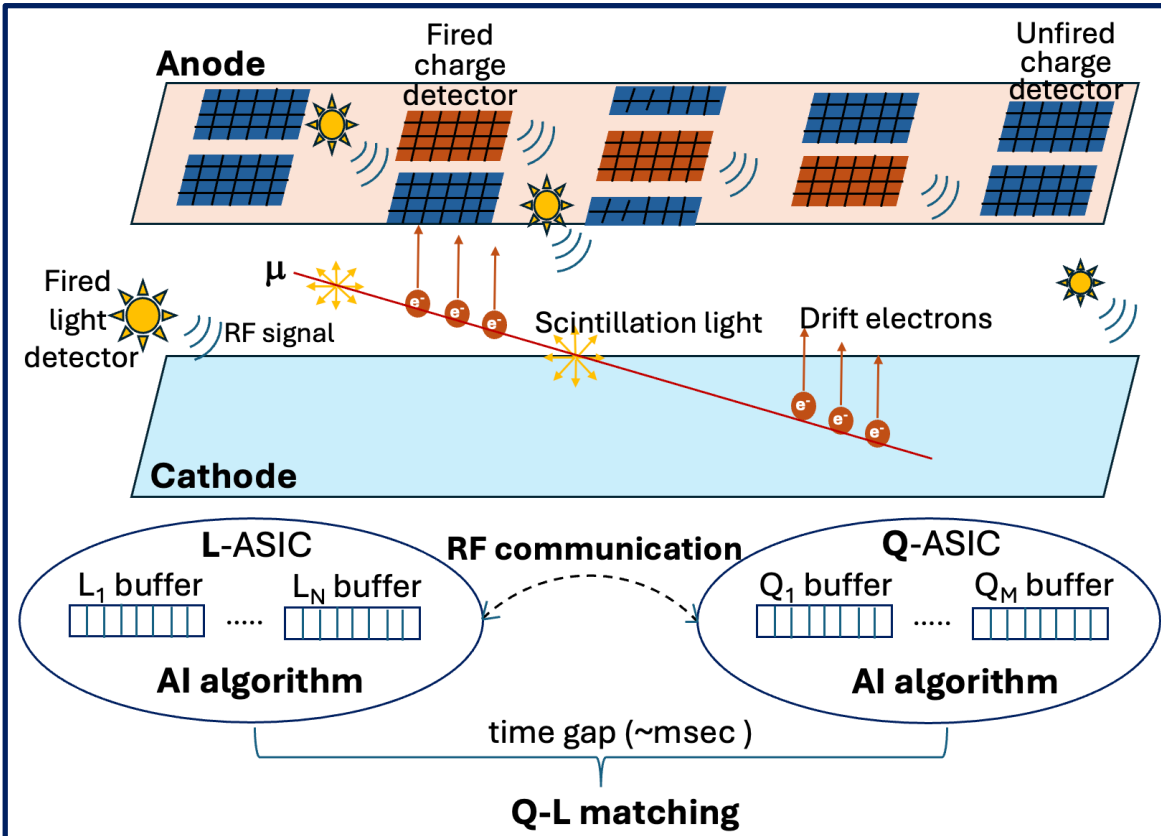
- Essential for subdetector communication
- **Enabling cable-free detector**

❑ Cryo dSiPM → Saving project budget

- ~10% that of commercial SiPM

AI/ML “*in-situ*” in LArTPC

Smart-Pixel TPC: Charge (Q) + Light (L) pixel detectors



- ❑ Q-L matching “*in-situ*”
 - ❑ Pattern recognition “*in-situ*”
 - Time
 - Space
 - Deposited charge & light
- RF network among all subdetector components are essential.

Test of RF Device(s) at LAr

❑ RF communication between Q & L detectors is essential for raw data reduction.

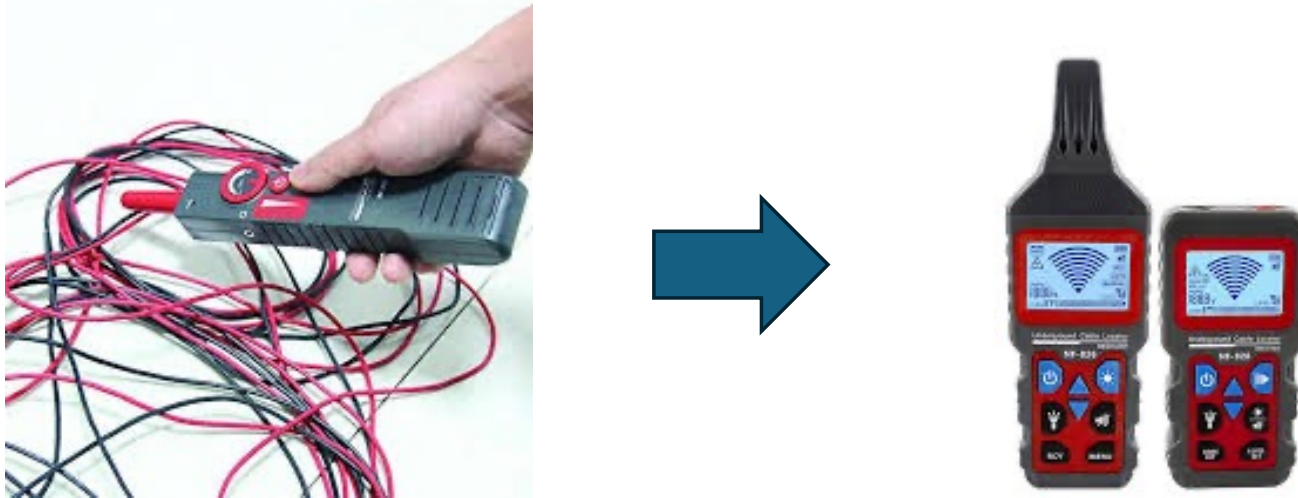
- We will start with a commercial RF device(s) to test it at LArTPC.
ex) LoRa
low power, cheap
- Through tests in LAr,
the device could be optimized to work properly in Cryo temperature.

RF Communication

❑ Not only RF communication between sub-detectors, we can consider **sending out raw data over RF network.**

→ This will allow us to build a **cable-free detector.**

We plan to test this during our R&D.



Here, imagine DUNE detector w/ & w/o cables.

Alternative Light Pixel Detector

SPAD: Single Photon Avalanche Diode

❑ [Cryo dSiPM](#)

→ Currently under-development
by Fermilab, EPFL, and Global Foundry

- [Pros:](#)

- Cheaper (~10% of commercial SiPMs)

- [Cons:](#)

- High dark count rate (→ need to measure it in LAr)
 - Need VUV wavelength shifter

Key Technologies in this R&D

❑ AI/ML on Chip (ASICs)

→ Reduce raw data volume “*in-situ*”

❑ RF Network

-- Communication between Q & L detector

→ essential for Q-L matching “*in-situ*”

-- Raw Data transfer

→ cable-free detector

❑ Digital CryoSPAD

-- Alternative to commercial SiPMs

-- not required for this R&D (but helps reduce budget)

Application to
any other
experiments

AI/ML Model to Hardware

Model Building

AI/ML model

+ Simulated data

HW-Aware Test

To optimize the model for given HW constraints (memory, speed, power,..)

Model Optimization (for resources)

+ Quantization
+ Pruning

Model Translation

Co-design model (physicist, AI expert, HW engineer)

HLS4ML (SW → HW)

+ Optimization
+ Profiling
+ Tuning

HW Implementation

AI/ML on FPGA, ASIC

HLS = high level synthesis

Timeline of “Smart-Pixel TPC” R&D

Phase-I: Feasibility Study

Build
AI/ML model
using
simulated data

HW-Aware Test,
Model Translation

Implement
& Test AI/ML
on FPGA

Wrapping up

Phase-II: Demonstrator

Implement
& Test AI/ML
on ASIC

Start

~1 yr

~1 yr

~1 yr

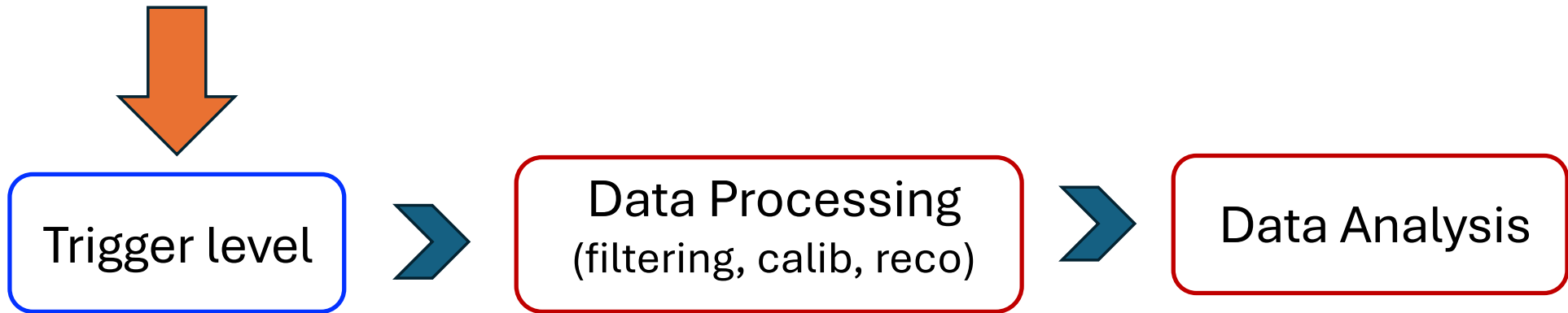
~2 yr

Finish

RF device test,
CryoSPAD test

Cable-free
data transfer test

AI/ML Start-to-End



Real-time anomaly detection

- * new physics search
- * Checking data quality
- * monitoring detector